

PMLL4148L; PMLL4448

High-speed switching diodes

Rev. 8 — 1 February 2011

Product data sheet

1. Product profile

1.1 General description

Single high-speed switching diodes, fabricated in planar technology, and encapsulated in small hermetically sealed glass SOD80C Surface-Mounted Device (SMD) packages.

Table 1. Product overview

Type number	Package	Configuration
PMLL4148L	SOD80C	single
PMLL4448		

1.2 Features and benefits

- High switching speed: $t_{rr} \leq 4$ ns
- Reverse voltage: $V_R \leq 75$ V
- Repetitive peak reverse voltage: $V_{RRM} \leq 100$ V
- Repetitive peak forward current: $I_{FRM} \leq 450$ mA
- Small hermetically sealed glass SMD package

1.3 Applications

- High-speed switching
- Reverse polarity protection

1.4 Quick reference data

Table 2. Quick reference data

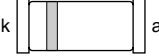

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current	[1]	-	-	200	mA
I_{FRM}	repetitive peak forward current		-	-	450	mA
V_R	reverse voltage		-	-	75	V
V_F	forward voltage					
	PMLL4148L	$I_F = 50$ mA	-	-	1	V
	PMLL4448	$I_F = 5$ mA	620	-	720	mV
		$I_F = 100$ mA	-	-	1	V
t_{rr}	reverse recovery time	[2]	-	-	4	ns

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] When switched from $I_F = 10$ mA to $I_R = 60$ mA; $R_L = 100$ Ω ; measured at $I_R = 1$ mA.

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode		
2	anode		

sym006

[1] The marking band indicates the cathode.

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PMLL4148L	-	hermetically sealed glass surface-mounted package;	SOD80C
PMLL4448	-	2 connectors	

4. Marking

Table 5. Marking codes

Type number	Marking code
PMLL4148L	marking band
PMLL4448	marking band

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	100	V
V_R	reverse voltage		-	75	V
I_F	forward current	[1]	-	200	mA
I_{FRM}	repetitive peak forward current		-	450	mA
I_{FSM}	non-repetitive peak forward current	square wave	[2]		
		$t_p = 1 \mu s$	-	4	A
		$t_p = 1 ms$	-	1	A
		$t_p = 1 s$	-	0.5	A

Table 6. Limiting values ...continued*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
P_{tot}	total power dissipation	$T_{\text{amb}} = 25\text{ °C}$	[1] -	500	mW
T_j	junction temperature		-	200	°C
T_{amb}	ambient temperature		-65	+200	°C
T_{stg}	storage temperature		-65	+200	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] $T_j = 25\text{ °C}$ prior to surge.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient	in free air	[1] -	-	350	K/W
$R_{\text{th(j-sp)}}$	thermal resistance from junction to solder point		-	-	300	K/W

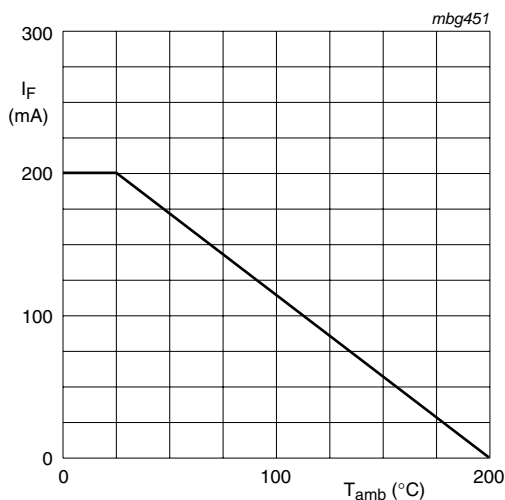
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 8. Characteristics *$T_{\text{amb}} = 25\text{ °C}$ unless otherwise specified.*

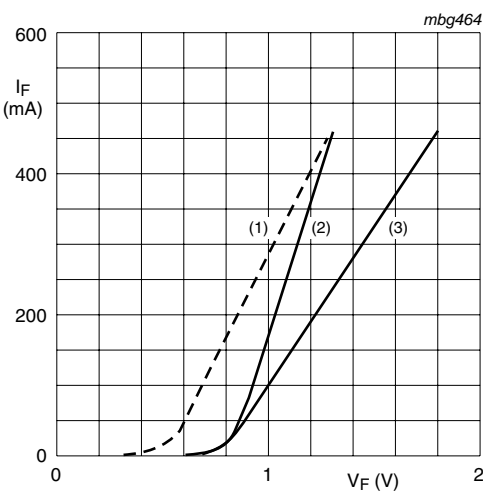
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage					
	PMLL4148L	$I_F = 50\text{ mA}$	-	-	1	V
	PMLL4448	$I_F = 5\text{ mA}$	620	-	720	mV
I_R	reverse current	$V_R = 20\text{ V}$	-	-	25	nA
		$V_R = 20\text{ V}; T_j = 150\text{ °C}$	-	-	50	μA
I_R	reverse current					
	PMLL4448	$V_R = 20\text{ V}; T_j = 100\text{ °C}$	-	-	3	μA
C_d	diode capacitance	$V_R = 0\text{ V}; f = 1\text{ MHz}$	-	-	4	pF
t_{rr}	reverse recovery time		[1] -	-	4	ns
V_{FR}	forward recovery voltage		[2] -	-	2.5	V

[1] When switched from $I_F = 10\text{ mA}$ to $I_R = 60\text{ mA}$; $R_L = 100\text{ Ω}$; measured at $I_R = 1\text{ mA}$.[2] When switched from $I_F = 50\text{ mA}$; $t_r = 20\text{ ns}$.



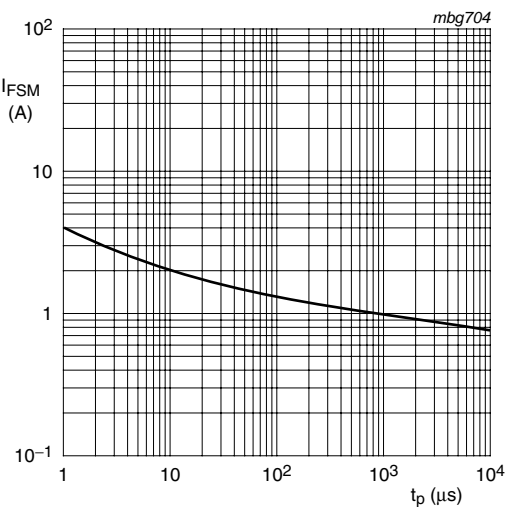
FR4 PCB, standard footprint

Fig 1. Forward current as a function of ambient temperature; derating curve



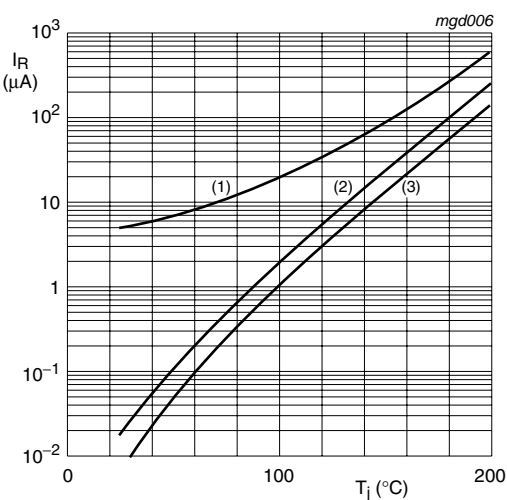
- (1) $T_j = 175\text{ }^{\circ}\text{C}$; typical values
- (2) $T_j = 25\text{ }^{\circ}\text{C}$; typical values
- (3) $T_j = 25\text{ }^{\circ}\text{C}$; maximum values

Fig 2. Forward current as a function of forward voltage



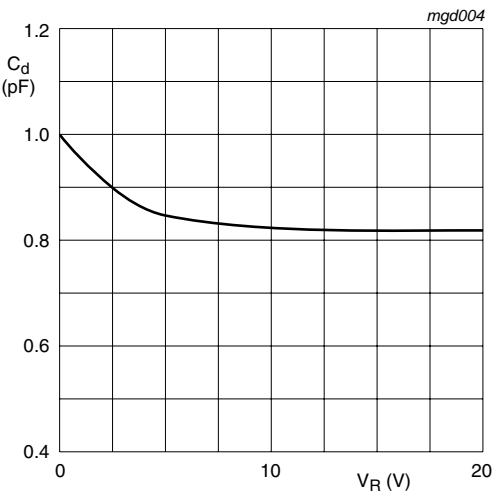
Based on square wave currents.
 $T_j = 25\text{ }^{\circ}\text{C}$; prior to surge

Fig 3. Non-repetitive peak forward current as a function of pulse duration; maximum values



- (1) $V_R = 75\text{ V}$; maximum values
- (2) $V_R = 75\text{ V}$; typical values
- (3) $V_R = 20\text{ V}$; typical values

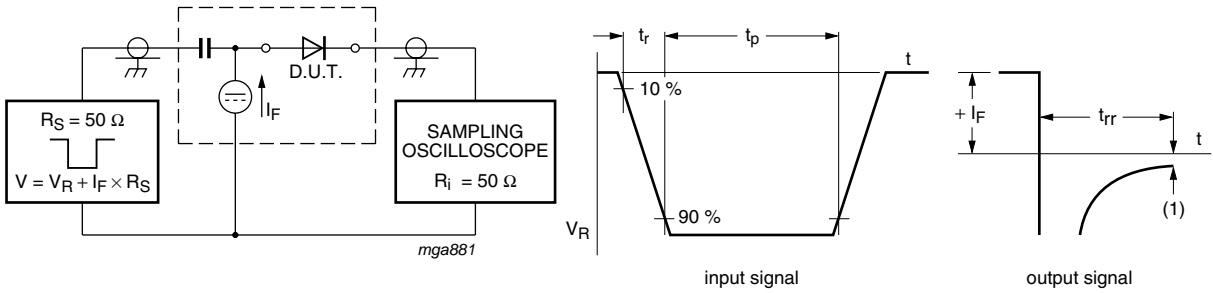
Fig 4. Reverse current as a function of junction temperature



$f = 1\text{ MHz}; T_j = 25\text{ }^\circ\text{C}$

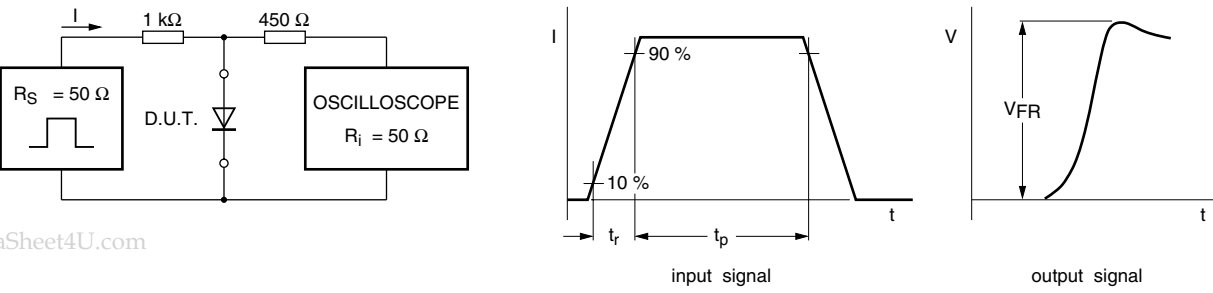
Fig 5. Diode capacitance as a function of reverse voltage; typical values

8. Test information



(1) $I_R = 1\text{ mA}$
Input signal: reverse pulse rise time $t_r = 0.6\text{ ns}$; reverse voltage pulse duration $t_p = 100\text{ ns}$; duty cycle $\delta \leq 0.05$
Oscilloscope: rise time $t_r = 0.35\text{ ns}$

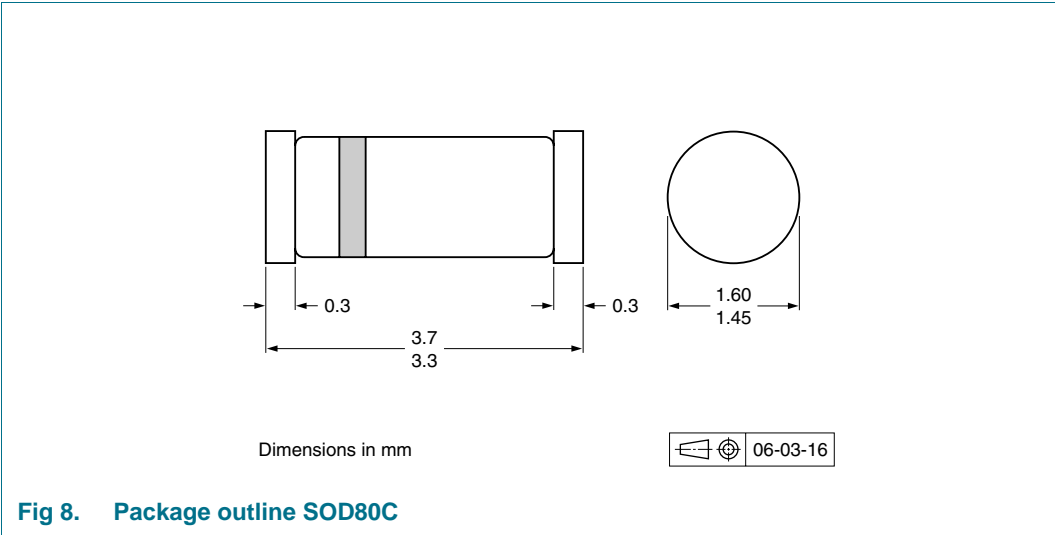
Fig 6. Reverse recovery time test circuit and waveforms



Input signal: forward pulse rise time $t_r = 20\text{ ns}$; forward current pulse duration $t_p \geq 100\text{ ns}$; duty cycle $\delta \leq 0.005$

Fig 7. Forward recovery voltage test circuit and waveforms

9. Package outline



10. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			2500	10000
PMLL4148L	SOD80C	4 mm pitch, 8 mm tape and reel	-115	-135
PMLL4448				

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering

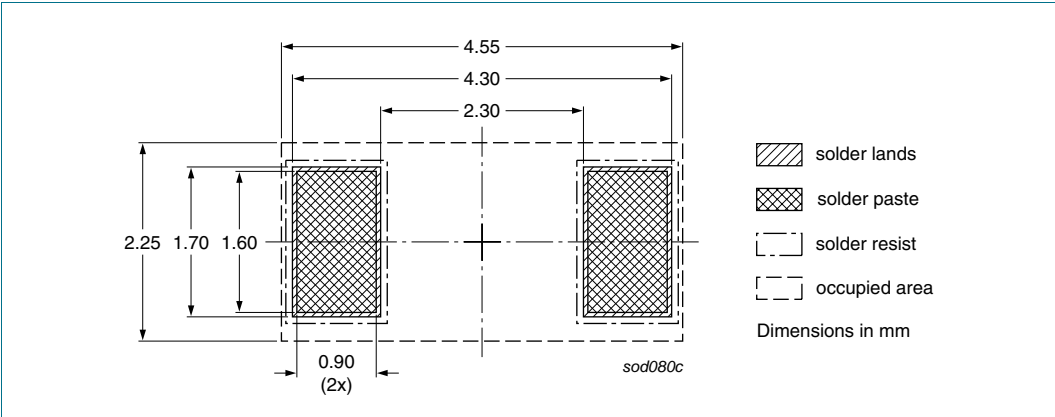


Fig 9. Reflow soldering footprint SOD80C

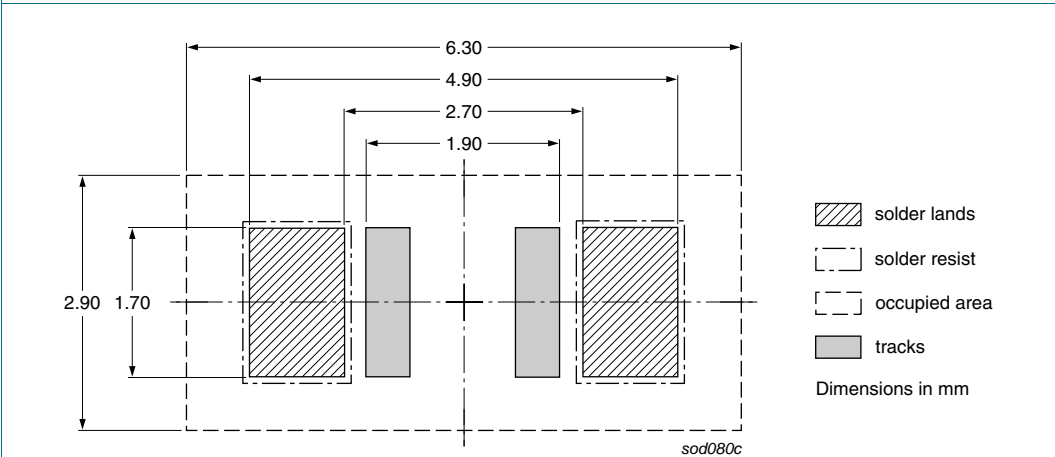


Fig 10. Wave soldering footprint SOD80C

12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMLL4148L_PMLL4448 v.8	20110201	Product data sheet	-	PMLL4148L_PMLL4448 v.7
Modifications:				
<ul style="list-style-type: none">• Section 4 "Marking": amended.• Figure 8: replaced by minimized outline drawing.• Section 13 "Legal information": updated.				
PMLL4148L_PMLL4448 v.7	20070131	Product data sheet	-	PMLL4148L_PMLL4448 v.6
PMLL4148L_PMLL4448 v.6	20050404	Product data sheet	-	PMLL4148L_4448 v.5
PMLL4148L_4448 v.5	20020123	Product specification	-	PMLL4148L_4448 v.4
PMLL4148L_4448 v.4	20001115	Product specification	-	PMLL4148 v.3
PMLL4148 v.3	19990527	Product specification	-	PMLL4148 v.2
PMLL4148 v.2	19960918	Product specification	-	PMLL4148 v.1
PMLL4148 v.1	19960423	Product specification	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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15. Contents

1	Product profile	1
1.1	General description	1
1.2	Features and benefits	1
1.3	Applications	1
1.4	Quick reference data	1
2	Pinning information	2
3	Ordering information	2
4	Marking	2
5	Limiting values	2
6	Thermal characteristics	3
7	Characteristics	3
8	Test information	5
9	Package outline	6
10	Packing information	6
11	Soldering	7
12	Revision history	8
13	Legal information	9
13.1	Data sheet status	9
13.2	Definitions	9
13.3	Disclaimers	9
13.4	Trademarks	10
14	Contact information	10
15	Contents	11